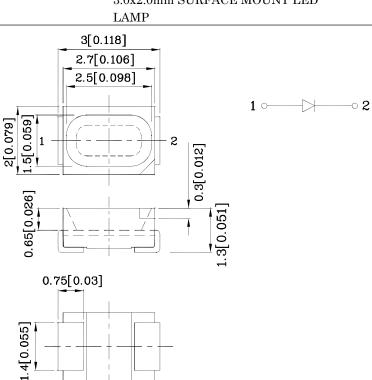


3.0x2.0mm SURFACE MOUNT LED

Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.





Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		CGS (InGaN)	Unit
Reverse Voltage	VR	5	v
Forward Current	IF	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA
Power Dissipation	PD	95	mW
Operating Temperature	ТА	-40 ~ +85	
Storage Temperature	Tstg	$-40 \sim +85$	°C

Operating Characteristics (TA=25°C)		CGS (InGaN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	3.2	v
Forward Voltage (Max.) (IF=20mA)	VF	3.8	v
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λP	500	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λD	505	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	28	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	45	pF

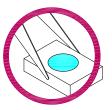
Part Number	Emitting Color	Emitting Material	Lens-color	Inte (IF=	ninous ensity 20mA) ncd	Wavelength nm λ P	Viewing Angle 2 0 1/2
		min.	typ.				
XZCGS105S	Green	InGaN	Water Clear	400	647	500	125°
Published Date :	AUG 02.2010	Drawi	ng No : XDSB5041	V1	Checked :	B.L.LIU	P.1/5



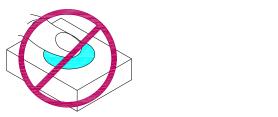
Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

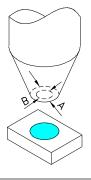




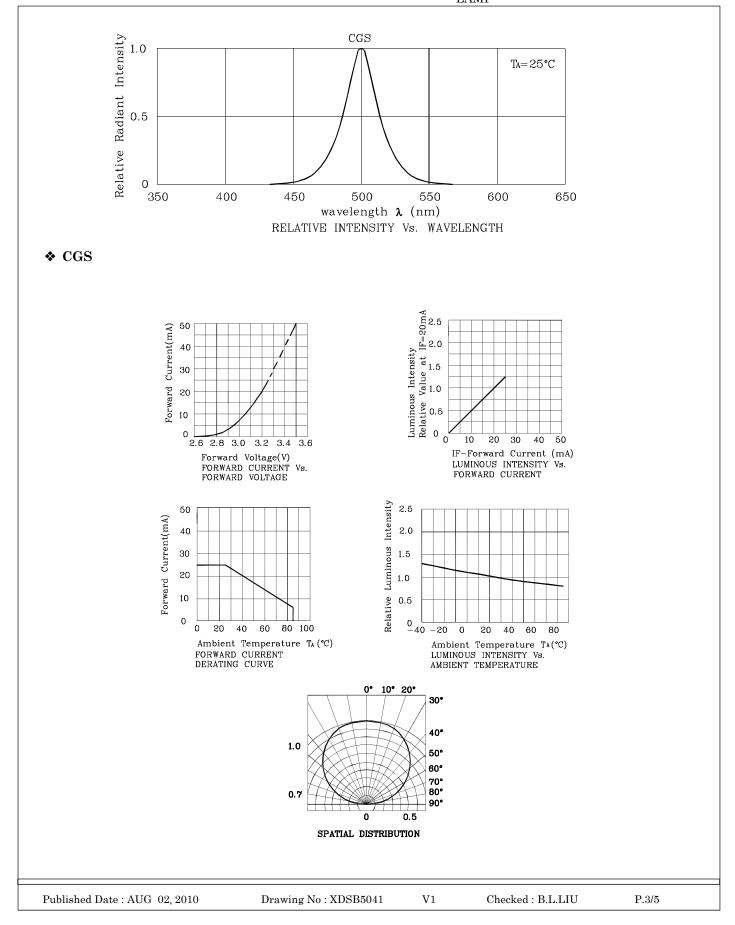
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



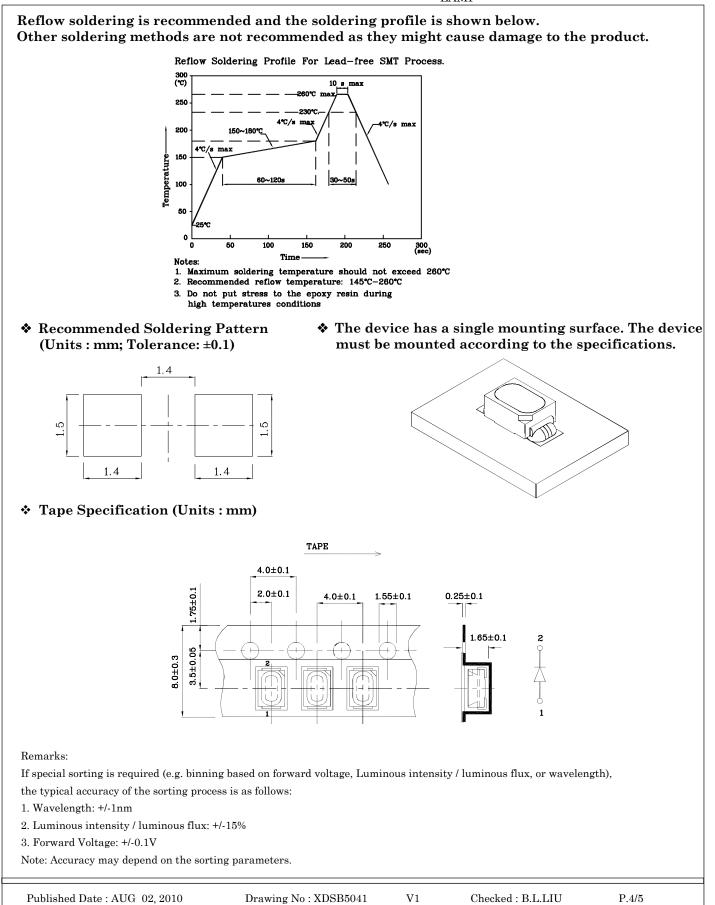
- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.













Part Number: XZCGS105S 3.0x2.0mm SURFACE MOUNT LED LAMP

